

#### **Description**

The IRLR7821PbF uses advanced trench technology

to provide excellent R<sub>DS(ON)</sub>, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

# D

TO-252-2L

#### **General Features**

 $V_{DS} = 30V I_{D} = 60 A$ 

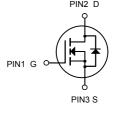
 $R_{DS(ON)} < 9m\Omega @ V_{GS}=10V$ 

## **Application**

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

# **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
IRLR7821PbF	TO-252-2L	HXY MOSFET	2500

# Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	30	V	
Vgs	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	60	А	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	40	А	
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> 13.6		
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> 11.4		
Ірм	Pulsed Drain Current <sup>2</sup>	Pulsed Drain Current <sup>2</sup> 110		
EAS	Single Pulse Avalanche Energy <sup>3</sup>	Single Pulse Avalanche Energy <sup>3</sup> 57.8		
las	Avalanche Current	Avalanche Current 34		
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	41	W	
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	issipation <sup>4</sup> 2.42		
Тѕтс	Storage Temperature Range -55 to 175		°C	
TJ	Operating Junction Temperature Range -55 to 175		°C	
Reja	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup> 62		°C/W	
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	3.6	°C/W	



#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

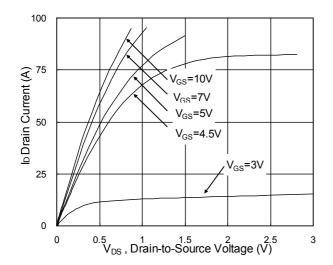
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
∆BVpss/∆TJ	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.027		V/°C
		V <sub>GS</sub> =10V , I <sub>D</sub> =30A		7	9	
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		11	14	$m\Omega$
V <sub>GS(th)</sub>	Gate Threshold Voltage	V V 1 250 A	1.2	1.5	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.8		mV/°C
less	Drain Cauras Laglaga Current	$V_{DS}$ =24V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		38		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.2	3.5	
Qg	Total Gate Charge (4.5V)			12.6	17.6	
Qgs	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		4.2	5.9	nC
Q <sub>gd</sub>	Gate-Drain Charge			5.1	7.1	
Td(on)	Turn-On Delay Time			4.6	9.2	
Tr	Rise Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3		12.2	22	
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =15A		26.6	53	ns
T <sub>f</sub>	Fall Time			8	16	
Ciss	Input Capacitance			1317	1843	
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		163	228	pF
Crss	Reverse Transfer Capacitance			131	183	
ls	Continuous Source Current <sup>1,5</sup>				55	Α
Ism	Pulsed Source Current <sup>2,5</sup>	$V_G=V_D=0V$ , Force Current			110	Α
VsD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			9.2		nS
Qrr	Reverse Recovery Charge	IF=30A , dl/dt=100A/μs , T <sub>J</sub> =25°C		2		nC

# Note:

- 1 .The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =34A
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



## **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

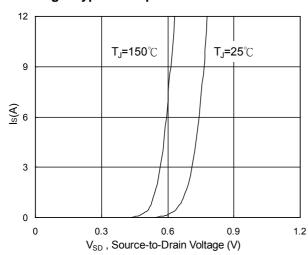


Fig.3 Forward Characteristics of Reverse

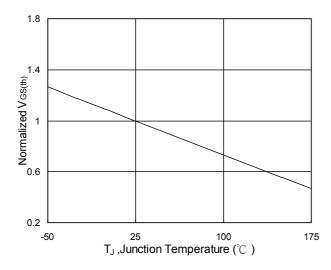


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

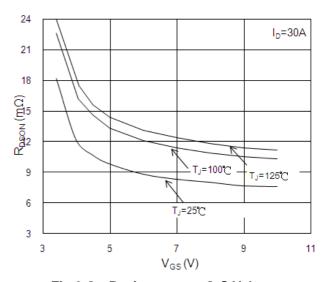


Fig.2 On-Resistance vs. G-S Voltage

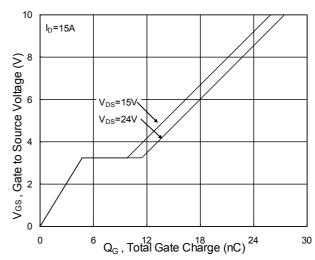


Fig.4 Gate-Charge Characteristics

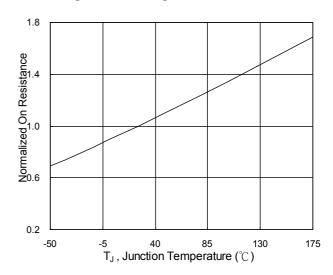
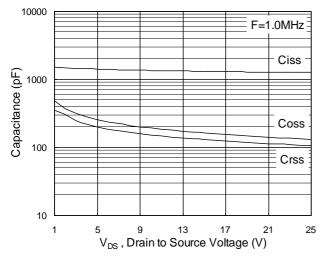


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



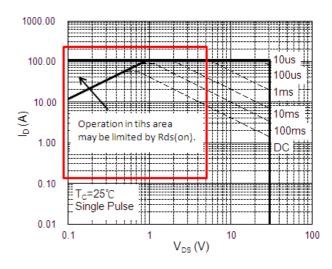


Fig.7 Capacitance

Fig.8 Safe Operating Area

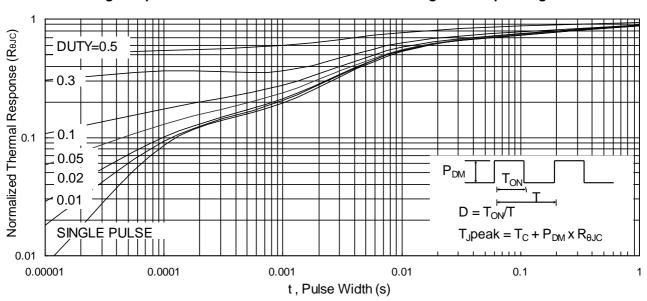
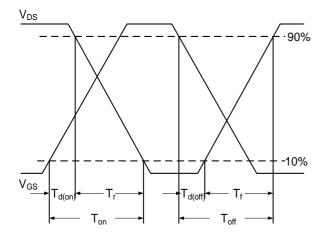
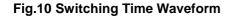


Fig.9 Normalized Maximum Transient Thermal Impedance





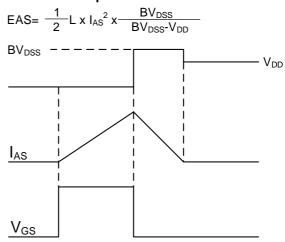
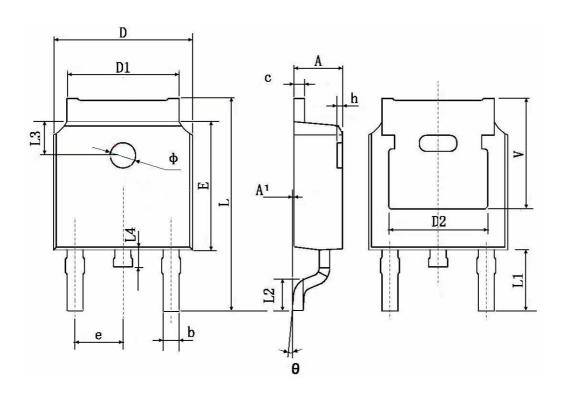


Fig.11 Unclamped Inductive Switching Waveform



# **TO-252-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
Α	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
С	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
е	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Ф	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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